STW75NF30



N-channel 300 V, 35 mΩ typ., 60 A STripFET™ II Power MOSFET in a TO-247 package

Datasheet - production data

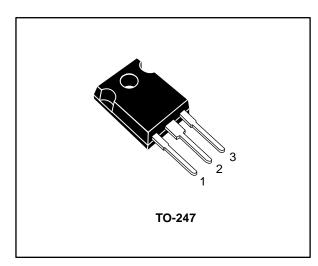
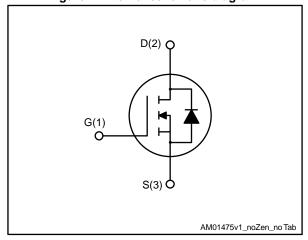


Figure 1: Internal schematic diagram



Features

Order code	V _{DS}	R _{DS(on)} max.	ΙD	Ртот
STW75NF30	300 V	45 mΩ	60 A	320 W

- Exceptional dv/dt capability
- 100% avalanche tested
- Low gate charge

Applications

Switching applications

Description

This Power MOSFET series realized with STMicroelectronics unique STripFET™ process is specifically designed to minimize input capacitance and gate charge. It is therefore ideal as a primary switch in advanced high-efficiency isolated DC-DC converters.

Table 1: Device summary

Order code	Marking	Package	Packing
STW75NF30	75NF30	TO-247	Tube

Contents STW75NF30

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STW75NF30 Electrical ratings

1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V _{DS}	Drain-source voltage	300	V
V _{GS}	Gate-source voltage	±20	V
ΙD	Drain current (continuous) at T _C = 25 °C	60	Α
ΙD	Drain current (continuous) at T _C = 100 °C	37.8	Α
I _{DM} ⁽¹⁾	Drain current (pulsed)	240	Α
Ртот	Total dissipation at T _C = 25 °C	320	W
dv/dt (2)	Peak diode recovery voltage slope	12	V/ns
T _{stg}	Storage temperature range	55 to 150	°C
Tj	Operating junction temperature range	- 55 to 150 °	

Notes:

Table 3: Thermal data

Symbol	Parameter	Value	Unit
R _{thj-case}	Thermal resistance junction-case	0.39	°C/W
R _{thj-amb}	Thermal resistance junction-ambient	50	°C/W

Table 4: Avalanche characteristics

Symbol	Parameter	Value	Unit
I _{AR}	Avalanche current, repetitive or non- repetitive (pulse width limited by $T_{\text{jmax.}}$)	50	А
Eas	Single pulse avalanche energy (starting T_j = 25 °C, I_D = I_{AR} , V_{DD} = 50 V)	400	mJ

 $[\]ensuremath{^{(1)}}\mbox{Pulse}$ width limited by safe operating area.

 $^{^{(2)}}$ $I_{SD} \leq 60$ A, di/dt ≤ 200 A/µs; $V_{DD} \leq 80\%$ $V_{(BR)DSS}$

Electrical characteristics STW75NF30

2 Electrical characteristics

(T_C= 25 °C unless otherwise specified)

Table 5: On/off-states

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$	300			V
	Zara gata valtaga drain	$V_{GS} = 0 \text{ V}, V_{DS} = 300 \text{ V}$			1	μΑ
IDSS	Zero-gate voltage drain current	$V_{GS} = 0 \text{ V}, V_{DS} = 300 \text{ V},$ $T_{C} = 125 \text{ °C}$ (1)			10	μΑ
I _{GSS}	Gate-body leakage current	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$			±100	nA
V _{GS(th)}	Gate threshold voltage	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	2	3	4	V
R _{DS(on)}	Static drain-source on- resistance	V _{GS} = 10 V, I _D = 30 A		35	45	mΩ

Notes:

Table 6: Dynamic

Symbol	Parameter	Parameter Test conditions		Тур.	Max.	Unit
Ciss	Input capacitance		ı	5930	-	pF
Coss	Output capacitance	$V_{DS} = 25 \text{ V}, f = 1 \text{ MHz},$	ı	837	-	pF
C _{rss}	Reverse transfer capacitance	Ves = 0 V	-	110	-	pF
Coss eq. (1)	Equivalent output capacitance	V _{DS} = 0 V to 240 V, V _{GS} = 0 V	-	462	-	pF
Rg	Intrinsic gate resistance	f = 1 MHz, I _D =0 A	•	1.55	-	Ω
Q_g	Total gate charge	$V_{DD} = 240 \text{ V}, I_D = 60 \text{ A}, V_{GS} = 0$	-	164	-	nC
Qgs	Gate-source charge	to 10 V (see Figure 15: "Test circuit for gate charge	-	36	-	nC
Q_{gd}	Gate-drain charge	behavior")	-	69	-	nC

Notes:

Table 7: Switching times

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(on)}	Turn-on delay time	V _{DD} = 150 V, I _D = 30 A	ı	115	ı	ns
tr	Rise time	$R_G = 4.7 \Omega$, $V_{GS} = 10 V$ (see Figure 14: "Test circuit for	-	87	-	ns
t _{d(off)}	Turn-off-delay time	resistive load switching times"	-	141	-	ns
t _f	Fall time	and Figure 19: "Switching time waveform")	1	101	1	ns

⁽¹⁾Defined by design, not subject to production test.

 $^{^{(1)}}$ Coss eq. is defined as a constant equivalent capacitance giving the same charging time as Coss when VDS increases from 0 to 80% VDSS.

Table 8: Source-drain diode

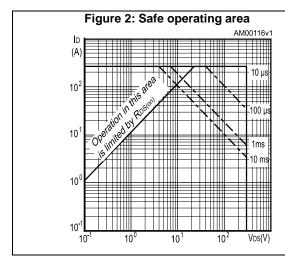
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I _{SD}	Source-drain current		ı		60	Α
I _{SDM} ⁽¹⁾	Source-drain current (pulsed)		-		240	Α
V _{SD} ⁽²⁾	Forward on voltage	V _{GS} = 0 V, I _{SD} = 60 A	ı		1.6	V
t _{rr}	Reverse recovery time	$I_{SD} = 60 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s},$	ı	252		ns
Qrr	Reverse recovery charge	V _{DD} = 60 V (see Figure 16: "Test circuit for inductive load	-	2.5		μC
I _{RRM}	Reverse recovery current	switching and diode recovery times")	ı	20		Α
t _{rr}	Reverse recovery time	$I_{SD} = 60 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s},$	-	316		ns
Qrr	Reverse recovery charge	$V_{DD} = 60 \text{ V}, T_j = 150 \text{ °C (see}$ Figure 16: "Test circuit for	-	3.7		μC
I _{RRM}	Reverse recovery current	inductive load switching and diode recovery times")	1	23.2		А

Notes:

 $^{^{(1)}}$ Pulse width is limited by safe operating area.

 $^{^{(2)}\}text{Pulse}$ test: pulse duration = 300 µs, duty cycle 1.5%.

2.1 Electrical characteristics (curves)



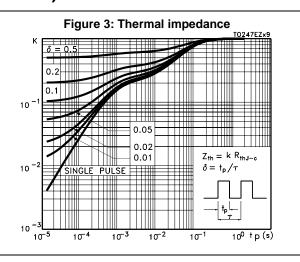


Figure 4: Output characteristics

AM00117v1

180

160

140

120

100

80

60

40

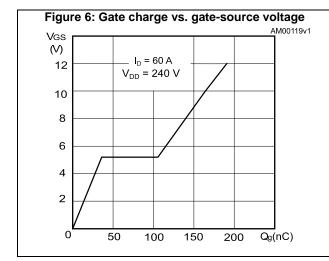
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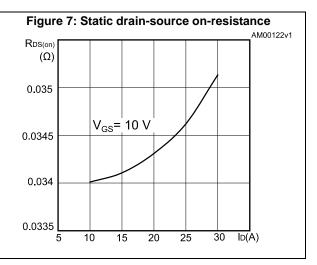
0

10

20

Vos(V)





STW75NF30 Electrical characteristics

Figure 8: Capacitance variations

C
(pF)

10⁴

10³

10²

10¹

10¹

10⁰

10¹

10²

Vbs(V)

Figure 9: Normalized gate threshold voltage vs temperature

VGS(th)
(norm)
1.1

I_D = 250 µA

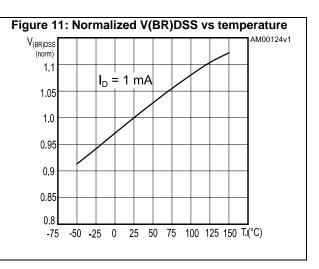
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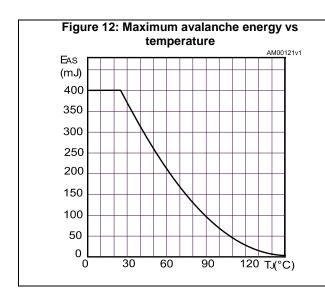
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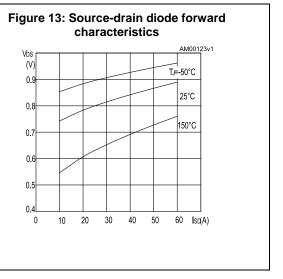
0.5

-75 -50 -25 0 25 50 75 100 125 150 TJ(°C)

Figure 10: Normalized on-resistance vs temperature $R_{DS(nn)}(\Omega)$ 2.5 $V_{GS} = 10 \text{ V}$ 2.0 $V_{GS} = 10 \text{ V}$ 1.5 $V_{GS} = 10 \text{ V}$ 2.75 -50 -25 0 25 50 75 100 125 150 T.(°C)







Test circuits STW75NF30

3 Test circuits

Figure 14: Test circuit for resistive load switching times

Figure 15: Test circuit for gate charge behavior

12 V 47 KΩ 100 N D.U.T.

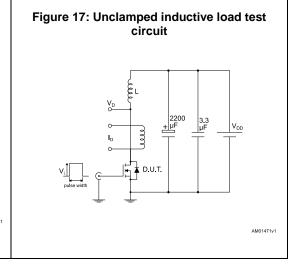
Vos 1 1 KΩ 100 N D.U.T.

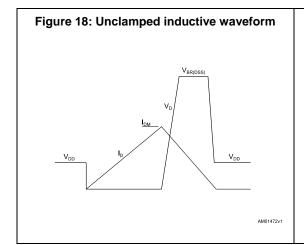
2200 V D.U.T.

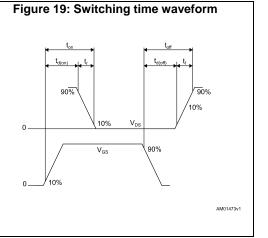
AM01469v1

switching and diode recovery times

Figure 16: Test circuit for inductive load







4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **www.st.com**. ECOPACK® is an ST trademark.

4.1 TO-247 package information

HEAT-SINK PLANE S øR Ľ2 *b1 b2* BACK VIEW 0075325_8

Figure 20: TO-247 package outline

Table 9: TO-247 package mechanical data

Dim		mm	
Dim.	Min.	Тур.	Max.
А	4.85		5.15
A1	2.20		2.60
b	1.0		1.40
b1	2.0		2.40
b2	3.0		3.40
С	0.40		0.80
D	19.85		20.15
Е	15.45		15.75
е	5.30	5.45	5.60
L	14.20		14.80
L1	3.70		4.30
L2		18.50	
ØP	3.55		3.65
ØR	4.50		5.50
S	5.30	5.50	5.70

STW75NF30 Revision history

5 Revision history

Table 10: Document revision history

Date	Revision	Changes
23-Oct-2007	1	First release.
27-May-2008	2	New value inserted in Table 6: Dynamic
15-Jul-2008	3	Document status promoted from preliminary data to datasheet.
24-Aug-2017	4	Updated Section 2.1: "Electrical characteristics (curves)" and Section 4.1: "TO-247 package information".

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